



Material Content Data Sheet



Sales Product Name		ICE2QR0665		Issued		20. July 2018		
MA#		MA000980954						
Package		PG-DIP-8-13		Weight*		557.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.023	1.08	1.08	10798	10798
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7704	
wire	non noble metal	copper	7440-50-8	174.475	31.28	32.10	312799	320984
	noble metal	gold	7440-57-5	0.259	0.05	0.05	464	464
	encapsulation	organic material	carbon black	1333-86-4	1.086	0.19		1946
encapsulation	plastics	epoxy resin	-	35.098	6.29		62924	
	inorganic material	silicondioxide	60676-86-0	325.652	58.39	64.87	583830	648700
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13439	13439
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1427	1427
glue	plastics	epoxy resin	-	0.350	0.06		628	
	noble metal	silver	7440-22-4	1.986	0.36	0.42	3560	4188
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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